

**AMENDMENTS TO THE ABSTRACT**

Please replace the paragraph at page 37, line 2, with the following rewritten paragraph:

-- Tapes ~~12, 12~~ are attached to a long support film ~~10~~, and the support film ~~10~~ is attached to frame member ~~18~~ at positions where the tape ~~12~~ to be stuck to an adherend, such as a semiconductor wafer, ~~14~~ is included in a frame of the ~~a~~ frame member ~~18~~. The support film ~~10~~ is pressed to stick the tape ~~12~~ to the adherend ~~14~~, and the support film ~~10~~ is released from the tape ~~12~~. The support film ~~10~~ is transferred and the above operations are repeated to stick the tapes ~~12, 12~~ to the respective adherends ~~14, 14~~. ~~The~~ In this manner, the tension to the tape ~~12~~ is diffused to the support film ~~10~~, and the frame member ~~18~~ blocks ~~causes~~ the tension of the support film ~~10~~ ~~out to~~ reside outside of the frame. Accordingly, the tape ~~12~~ stuck to the adherend ~~14~~ has reduced residual stress and the adherend such as a thin semiconductor wafer to which the tape has been stuck can be prevented ~~is~~ free from warpage which would otherwise be caused by a tape applied under tension. --